

WHAT IS CLAIMED IS:

- 1 *Sub A1* 1. A chip device comprising:
2 a. a leadframe comprising a plurality of leads;
3 b. a first die coupled to a first side of the leadframe with solder;
4 c. a second die coupled to a second side of the leadframe with solder;
5 and
6 d. a molded body surrounding at least a portion of the leadframe and
7 the dies.

- 1 2. The chip device of claim 1 wherein at least one of the dies is a
2 *Sub A1* bumped die.

- 1 3. The chip device of claim 2 wherein both dies are bumped dies.

- 1 4. The chip device of claim 1 wherein the first die is a MOSFET.

- 1 5. The chip device of claim 4 wherein the second die is a controller
2 IC.

- 1 6. The chip device of claim 1 wherein a drain region of the first die is
2 exposed through the molded body.

- 1 7. A method of making a chip device, the method comprising:
2 providing a leadframe comprising a plurality of leads;
3 placing a first die on a first side of the leadframe with first solder
4 therebetween;
5 reflowing the first solder at a first temperature;
6 flipping the leadframe;

7 placing a second die on a second side of the leadframe with second solder
8 therebetween; and
9 reflowing the second solder at a second temperature lower than the first
10 temperature.

1 8. A method of making a chip device, the method comprising:
2 providing a leadframe comprising a plurality of leads;
3 flipping a first die on a first side of the leadframe with first solder
4 therebetween;
5 reflowing the first solder at a first temperature;
6 flipping the leadframe;
7 ~~flipping a second die on a second side of the leadframe with second solder~~
8 therebetween;
9 reflowing the second solder at a second temperature lower than the first
10 temperature; and
11 placing a molded body around at least a portion of the leadframe and the
12 dies.